

June 22, 2023

Attn: FCC Office of Engineering and Technology / UL Verification Services TCB

Ref: Class 2 Permissive Change for FCC ID: **2AC8R-NFC2**  
Original approval date: May 13, 2019  
Additional C2PC dates: none  
Applicant: Elkay Manufacturing Company

To Whom It May Concern

This is to request for a Class II Permissive Change to address the following proposed changes to Elkay's **Filter NFC Board**:

1. A new alternate Microprocessor Crystal at Y3 from the same manufacturer as the original with identical electrical and radio characteristics but with a larger SMD pad footprint. That is, the new alternate is not pin-to-pin compatible.
2. Enlarge the PCB trace-pads at Y3 to accommodate both the original and new alternate Microprocessor Crystal.

The reason for these changes is that the original Microprocessor Crystal has increasingly long lead-times to procure and has become more difficult to obtain in the required production volumes.

To clarify, this request addresses all nine conditions of FCC's guidance for permissive change, Notification# 202109-001, titled *Class II Permissive Change for PCB and Part Modification and PAG C2PCXPAG C2PCPX*, see our finding on page two.

Additionally, to help compare the original and alternate Microprocessor Crystals, see attached technical datasheets on pages 3-5 and pages 6-9, respectively. And for details of the enlarged PCB trace-pads at Y3, see the Schematic document. And for images of the changed Elkay Filter NFC Board, see Internal Photos document.

The following tests were performed to validate the fundamental frequency, primary modulator circuit, maximum power, or field strength ratings have remained unchanged:

- Radiated, conducted emissions: FCC Part 15 Subpart C.
- Frequency stability

If any questions regarding this application, please feel free to contact me.

Sincerely yours,



René G. Laude  
Senior Compliance Engineer  
Elkay Manufacturing Company

Conditions per FCC's PAG C2PCPX Notification# 202109-001	Findings
1) The requirements of § 2.1043 are fulfilled, i.e., the device's block functions for the fundamental frequency, primary modulator circuit, maximum power, or field strength ratings shall remain unchanged.	Compliant
2) Transmitter PCB layout and parts changes are only permitted if there is no change in identifying a device's form, functional specification, as initially granted or previously approved under a Class II permissive change.	Compliant
3) PCB changes are limited to non-substantive modifications layout changes to the same size physical circuit board previously granted.	Compliant
4) C2PCPX is not permitted to add, remove, augment, or change capabilities, such as transmitters, increased bandwidth, additional rule parts, bands, etc..	Compliant
5) In the PAG submission for item C2PCPX, the applicant shall provide complete information on testing demonstrating that the proposed changes for fundamental emissions are unchanged within the normal, acceptable tolerances and out-of-band; emissions do not exceed the appropriate limits. The PAG submission shall include all applicable test reports and internal photos.	Compliant
6) The modified device shall not be marketed under the existing grant of certification before confirmation that the C2PCPX PAG is approved and granted.	Compliant
7) Software Defined Radio (SDR) grants that use the C2PCPX procedure are not permitted to make subsequent Class III permissive changes.	N/A
8) The C2PCPX PAG procedure has no impact on the provisions of V) of this publication for non-SDR software-only changes; thus, adding an equipment class when related to rule changes is still permitted.	N/A
9) Class I permissive changes are not permitted <sup>3</sup> under this C2PCPX procedure.	Compliant

# CERAMIC SMD MICRO MINIATURE MICROPROCESSOR CRYSTAL

**ABM7**Pb in Glass  
(exempt per RoHS 2002/95/EC Annex (5))**RoHS/RoHS II Compliant**

ABM7

6.0 x 3.5 x 1.4mm

**Moisture Sensitivity Level (MSL) – This product is Hermetically Sealed and not Moisture Sensitive - MSL = N/A: Not Applicable****FEATURES:**

- Low in height (1.4 mm max.)
- Ceramic package assures high reliability
- Small size SMD, suitable for high density applications
- Superior heat-resistant glass sealing
- Wide operating temperature available

**APPLICATIONS:**

- Computers, Modems, Communication equipment
- Thin equipment
- Industrial wide temperature applications

**STANDARD SPECIFICATIONS:**

Parameters	Minimum	Typical	Maximum	Units	Notes
Frequency Range	8.000		48.000	MHz	Fundamental AT-cut
Operating Temperature	-10		+60	°C	See options
Storage Temperature	-55		+125	°C	
Frequency Tolerance @ +25°C	-50		+50	ppm	See options
Frequency Stability over the Operating Temperature (ref. to +25°C)	-50		+50	ppm	See options
Equivalent series resistance	See table 1 below			Ω	
Shunt capacitance (C0)			7	pF	
Load capacitance (CL)		18		pF	See options
Drive Level		10	100	μW	
Aging@25°C±3°C			±5	ppm	First year
Insulation Resistance	500			MΩ	@ 100Vdc

**Table 1**

Frequency (MHz)	ESR(Ω) max.
8.000 – 9.999	100
10.000 – 11.999	80
12.000 – 15.999	60
16.000 – 48.000	50

 **ABRACON**

5101 Hidden Creek Ln Spicewood TX 78669  
Phone: 512-371-6159 | Fax: 512-351-8858  
For terms and conditions of sales, please visit:  
[www.abracon.com](http://www.abracon.com)

**REVISED: 09-03-19**

ABRACON IS  
ISO9001-2015  
CERTIFIED

# CERAMIC SMD MICRO MINIATURE MICROPROCESSOR CRYSTAL

**ABM7**

Pb in Glass  
(exempt per RoHS 2002/95/EC Annex (5))

**RoHS/RoHS II Compliant**

ABM7

6.0 x 3.5 x 1.4mm

## ► OPTIONS AND PART IDENTIFICATION: (left blank if standard)

ABM7- [ ] MHz - [ ] - [ ] - [ ] - [ ] - [ ]

### Frequency in MHz

e.g. 14.31818MHz  
26.000MHz

### Load Capacitance (pF)

Please specify CL in pF or  
S for series (8 to 33pF)  
Please contact ABRACON for  
other values

### Custom ESR if other than standard

R  
 Specify a value in  $\Omega$   
(e.g.: R40)

### Operating Temp.

- E: 0°C ~ +70°C
- B: -20°C ~ +70°C
- C: -30°C ~ +70°C
- N: -30°C ~ +85°C
- D: -40°C ~ +85°C
- J (\*\*\*): -40°C ~ +105°C

(\*\*\*): ±100 ppm only

Please check with Abracon for  
availability for non-standard  
frequencies with these operating  
temperature options.

### Freq. Tolerance

- 1: ± 10 ppm
- 7: ± 15 ppm
- 2: ± 20 ppm
- 3: ± 25 ppm
- 4: ± 30 ppm

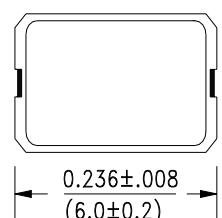
### Freq. Stability

- U: ± 10 ppm (\*)
- G: ± 15 ppm (\*\*)
- X: ± 20 ppm
- W: ± 25 ppm
- Y: ± 30 ppm
- H: ± 35 ppm
- Q: ± 100 ppm

(\*) -10°C to 60°C only.

(\*\*) Contact ABRACON for  
availability for  
-40°C to +85°C

## ► OUTLINE DIMENSION:



0.138±.008  
(3.5±0.2)

0.236±.008  
(6.0±0.2)



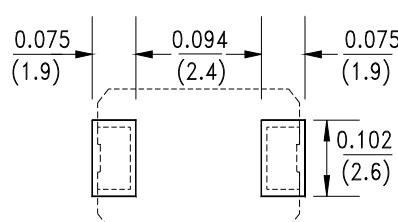
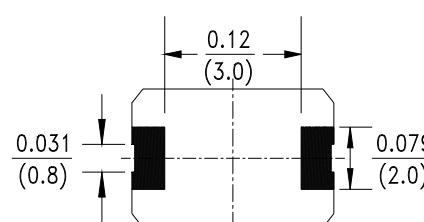
0.055 MAX  
(1.4 MAX)

CONNECTION



Dimensions: inches (mm)

Recommended land pattern



**Note: Due to the availability of raw materials, this part may be manufactured with the chamfer on pin 1.  
Be advised that this does not affect the electrical characteristics of the crystal in any way.**

# CERAMIC SMD MICRO MINIATURE MICROPROCESSOR CRYSTAL

**ABM7**

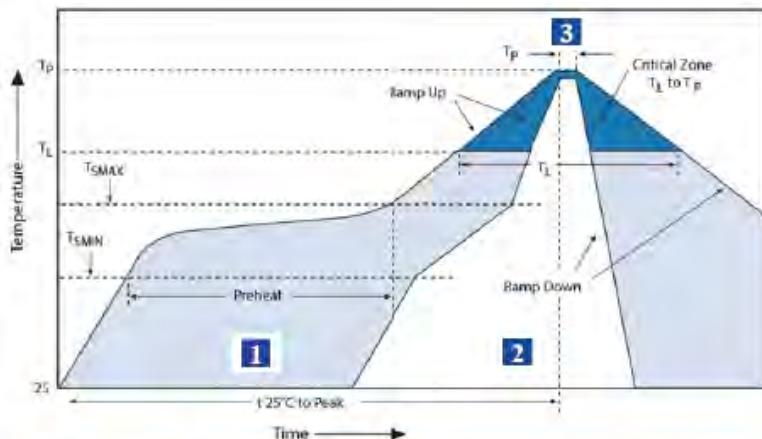
Pb in Glass  
(exempt per RoHS 2002/95/EC Annex (5))

**RoHS/RoHS II Compliant**

ABM7

6.0 x 3.5 x 1.4mm

## REFLOW PROFILE:



Zone	Description	Temperature	Times
1	Preheat	$T_{SMIN} \sim T_{MAX}$ $150^{\circ}C \sim 180^{\circ}C$	60 - 120 sec.
2	Reflow	$T_L$ $230^{\circ}C$	30 ~ 40 sec.
3	Peak heat	$T_p$ $264^{\circ}C \pm 5^{\circ}C$	10 sec. MAX

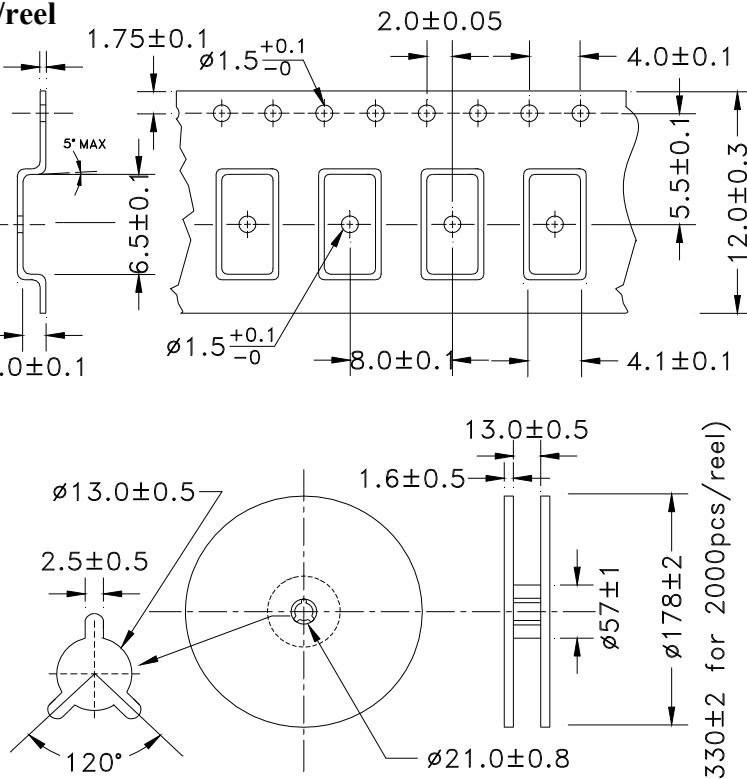
## TAPE & REEL:

Packaging:

**T: 1000pcs/reel**

**T2: 250pcs/reel**

FEEDING (PULL) DIRECTION



Dimensions: mm

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# SMD MICROPROCESSOR CRYSTAL

ABLS7M2



RoHS / RoHS II Compliant



7.0 x 4.1 x 2.0mm

Moisture Sensitivity Level (MSL) – This product is Hermetically Sealed and not Moisture Sensitive - MSL = N/A: Not Applicable

## FEATURES:

- **Reduced footprint from ABLS (standard HC/49US package) by 50%**
- Low profile: 2.0mm max. height
- Suitable for RoHS compliant reflow
- Tight stability & extended temperature options
- High reliability & Cost effective
- Resistance welded metal package

## APPLICATIONS:

- Wireless Applications
- Home electronics
- Computers, modems, and communications
- Microprocessors

## STANDARD SPECIFICATIONS:

Parameters	Minimum	Typical	Maximum	Units	Notes	
Frequency Range*	12.0		40.0	MHz		
Standard Frequencies	12.0, 12.288, 13.5, 13.56, 14.31818, 14.7456, 16.0, 18.432, 20.0, 20.5, 24.0, 24.576, 25.0, 26.0, 27.0			MHz		
Operation Mode	Fundamental (AT-cut)					
Operating Temperature	0		+70	°C	See options	
Storage Temperature	-40		+125	°C		
Frequency Tolerance @+25°C	-50		+50	ppm	See options	
Frequency Stability over the Operating Temperature (ref. to +25°C)	-50		+50	ppm	See options	
Equivalent series resistance (R1) @+25°C				Ω	12.000 ~ 16.000MHz	
					16.001 ~ 30.000MHz	
					30.001 ~ 40.000MHz	
Shunt capacitance (C0)			5	pF		
Load capacitance (CL)	18			pF	Standard (See options if other than STD)	
Drive Level		50	100	μW		
Aging	-5		+5	ppm	@25°C±3°C First year	
Insulation Resistance	500			MΩ	@ 100Vdc ± 15V	
Drive level dependency (DLD)	10nw ~ 100uw, 12 points Change in ESR (Maximum - Minimum) over DLD range < 30% ESR max.					

\* Please contact Abracan for other frequencies.



### ► PART IDENTIFICATIONS: (left blank if standard)

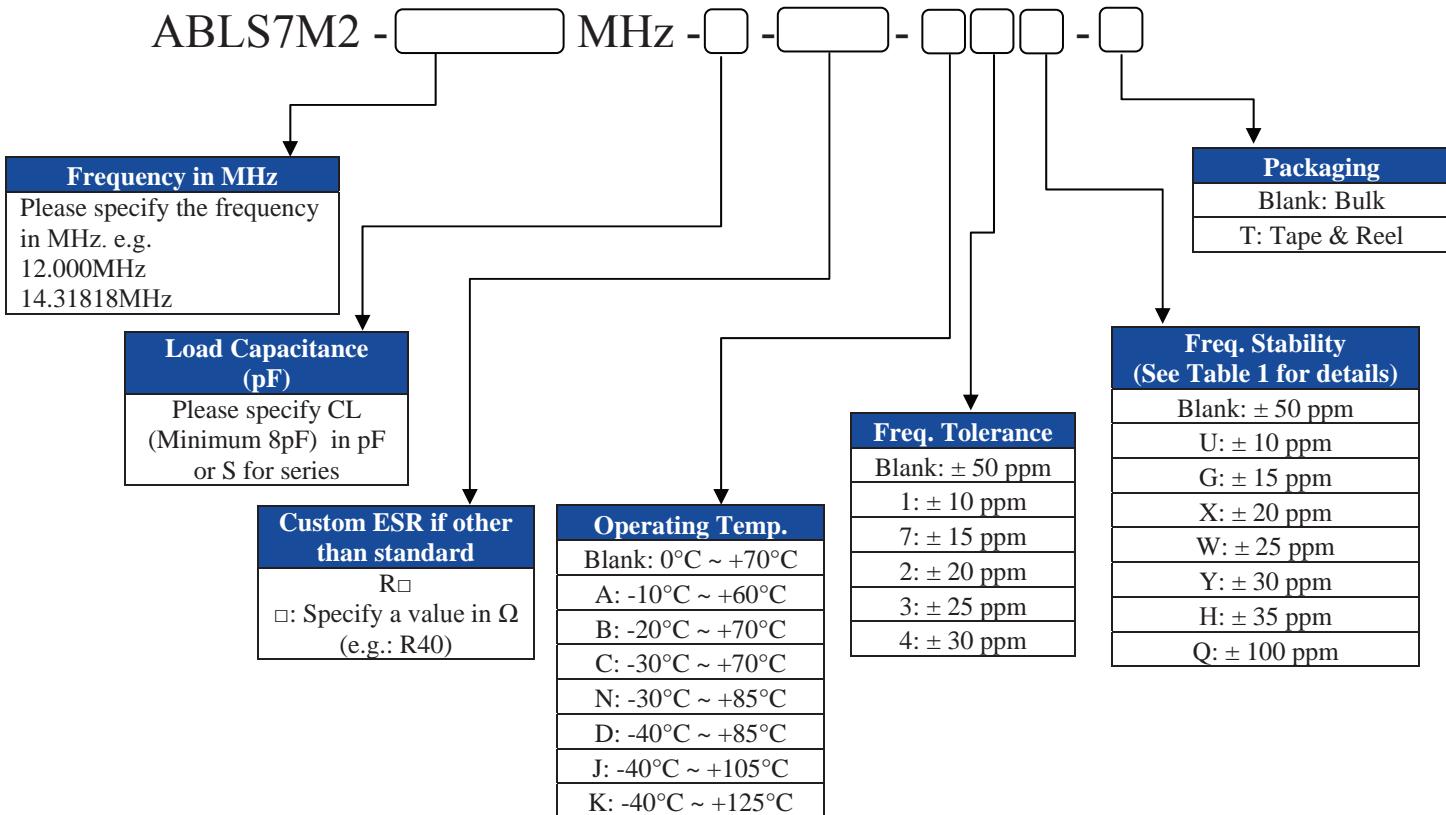


Table 1 Available Combinations of Operating Temp. and Freq. Stability

Operating Temp.	Freq. Stability							
	U:±10ppm	G:±15ppm	X:±20ppm	W:±25ppm	Y:±30ppm	H:±35ppm	Std.:±50ppm	Q:±100ppm
A: -10°C ~ +60°C	√	√	√	√	√	√	√	√
Std.: 0°C ~ +70°C	√	√	√	√	√	√	√	√
B: -20°C ~ +70°C		√	√	√	√	√	√	√
C: -30°C ~ +70°C			√	√	√	√	√	√
N: -30°C ~ +85°C					√	√	√	√
D: -40°C ~ +85°C					√	√	√	√
J: -40°C ~ +105°C							√	√
K: -40°C ~ +125°C								√

Note: Please contact Abracon for other frequency stability and operating temperature range options.

# SMD MICROPROCESSOR CRYSTAL

ABLS7M2

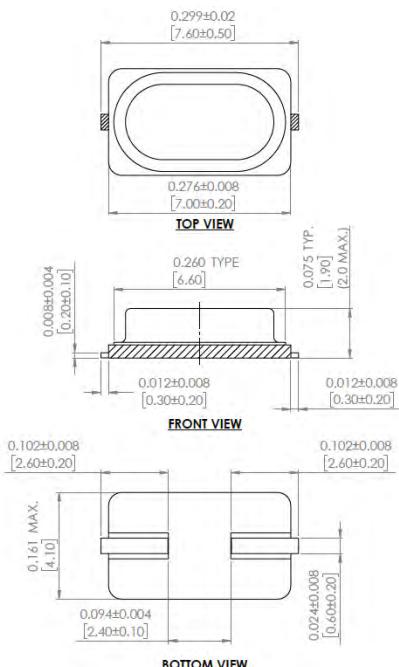


RoHS / RoHS II Compliant

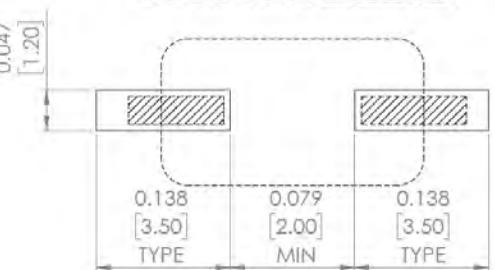


7.0 x 4.1 x 2.0mm

## OUTLINE DIMENSION:



### RECOMMENDED LAND PATTERN

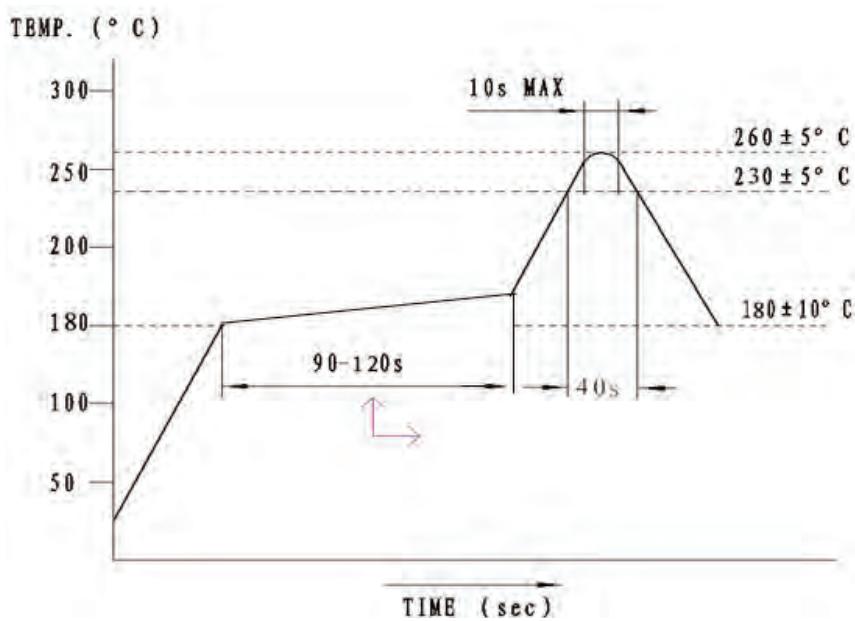


### Actual Size Comparison

	ABLS
	11.4 x 4.7 x 4.2 mm
	ABLS7M2
	7.0 x 4.1 x 2.0 mm

Dimension: inches [mm]

## REFLOW PROFILE:



# SMD MICROPROCESSOR CRYSTAL

ABLS7M2



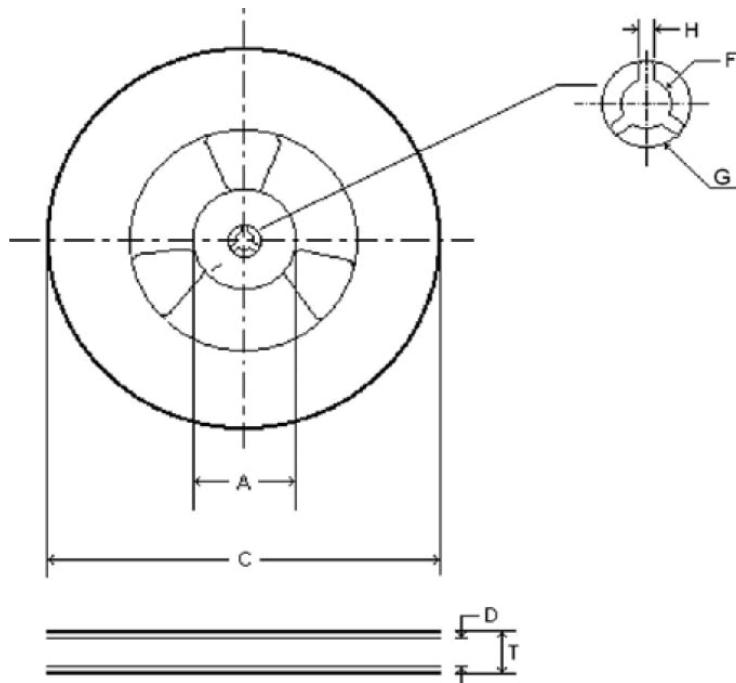
RoHS / RoHS II Compliant



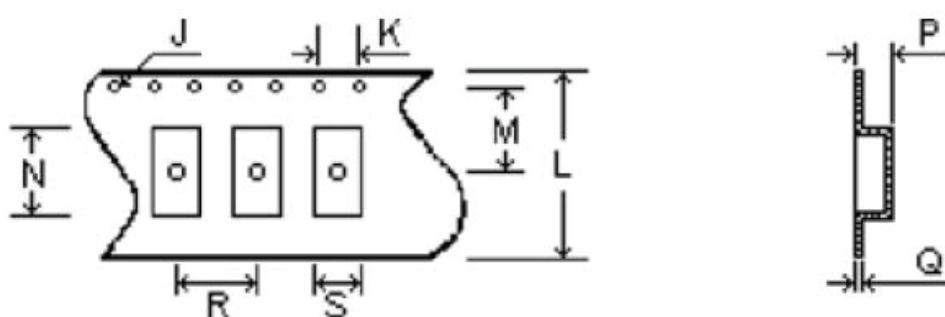
7.0 x 4.1 x 2.0mm

## ➤ TAPE & REEL:

T = tape and reel (3000pcs/reel)



No.	Dimensions (mm)
A	$100 \pm 1.0$
C	$330 \pm 2.0$
D	$16.4 \pm 1.0$
T	$20.4 \pm 0.5$
F	$13.0 \pm 0.2$
G	$20.2 \text{ min.}$
H	$1.5 \text{ min.}$



No.	Dimensions (mm)
J	$\varnothing 1.5$
K	$4.0 \pm 0.1$
L	$16.0 \pm 0.3$
M	$7.5 \pm 0.1$
N	$9.4 \pm 0.1$
P	$2.5 \pm 0.1$
Q	$0.3 \pm 0.05$
R	$8.0 \pm 0.1$
S	$4.4 \pm 0.1$

Dimensions: mm

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